

Usages Policy:

Step I (at CSIR-NPL)	
Process	DC magnetron sputtering
Equipment Name	EXCEL Instruments (custom designed)
Processed at Lab/Center/Institute	PLD Lab, CSIR-NPL
Equipment Ambiance [Cleanroom Classes 10,100,1000,etc; Semi clean; Not Clean]	Ultra-thin superconducting films are grown on Sapphire substrate using DC magnetron sputtering facility at CSIR-NPL in semi clean environment. Samples were grown in 6N pure argon or argon/N ₂ mixture
Highest Temp Observed by Sample/Substrate (°C)	600 – 800 °C (in high vacuum or in argon or argon/N ₂ mixture)
Equipment Usage Policy at the lab [What all materials have so far allowed in the system from its installation date, what restrictions incoming sample has, what cleaning is done prior if any, etc.]	Metals and metal nitrides
Process Description	DC magnetron sputtering in argon or argon/N ₂ mixture

Step II (at IITBNF)				
Process Nos.	Process Sequence	Tools Required*	Contamination Category of tools*	Process Parameters
1	PMMA coating	Spin coater		
2	Pattern writing using EBL	EBL		
3	Pattern developing	Developer solution		
4	Cr/Au deposition for contact pads	Thermal or e-beam evaporation		
5	Lift-off	Lift-off in acetone		
6	HSQ coating	Spin coater		
7	Pattern writing using EBL	EBL		
8	Pattern developing	Developer solution		
9	Selective removal of thin films for meander formation	Reactive ion etching		

Step III (at IITBNF) Characterization Process Details			
Sample No.	Sample Name	Characterization Equipment	Required Characterization Parameters (e.g. step height for Profilometer/scan angle for XRD/ feature size for SEM)
	Fabricated samples at IITBNF	SEM	Observation of meander patterns [patterned area: 10micron X 10micron] for its uniformity, continuity, defects, line width, line spacing etc.